

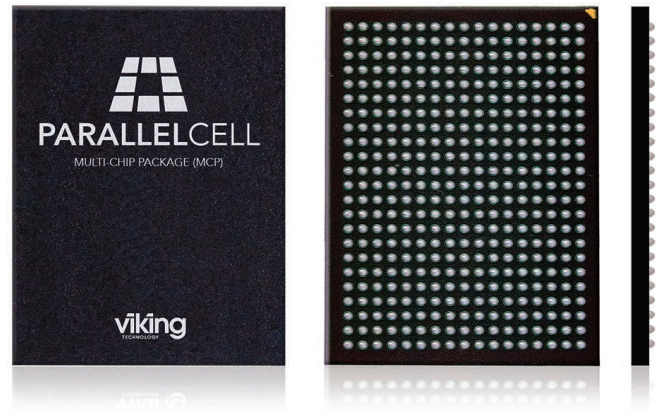
PRODUCT BRIEF | MCP

# PARALLELCELL

## MULTI-CHIP PACKAGE (MCP)

Military Grade Ultra High Density Memory Solution for Embedded Applications

Viking Technology ParallelCell Multi-Chip Package (MCP) is part of the extreme density line of DDR4 memory products optimized for the embedded, industrial, and military/aerospace markets. ParallelCell products achieve significantly higher memory performance and density per cubic inch than conventional memory DIMMs. These performance and density milestones will critically change the way future system hardware is designed and deployed.

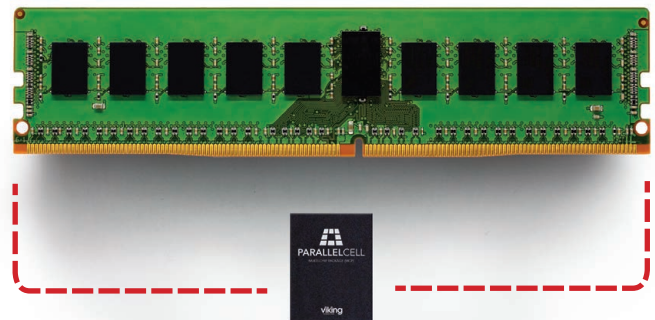


### BENEFITS

Very small footprint: Saves up to 85% board space vs. Standard DIMM Modules	Very high memory capacity per cu. in.	Very high memory bandwidth per cu. in.
Rugged: Soldered-down – No DIMM connector	Superior signal integrity	Lower cost motherboard due to easier DDR routing

SPEEDS		VOLTAGE
DDR4	2133/2400/2667	1.2V
TEMPERATURE		
Industrial	-40°C to 85°C	
Extended	-40°C to 105°C	
Military	-55°C to 125°C	
Commercial	0°C to 70°C	
CAPACITY		
4GB/8GB/*16GB/*32GB		

\* 16GB/32 GB Capacities planned for future development



Available in: 15mm x 20mm and 13mm x 20mm

Made in the USA 

# PARALLELCELL MULTI-CHIP PACKAGE (MCP)

Military Grade Ultra High Density Memory Solution for Embedded Applications

## THE VIKING VALUE ADVANTAGE

- ▶ ITAR & AS9100, TL 9000 & ISO 14001 Certified
- ▶ USA based R&D, Development & Production
- ▶ Advanced Packaging Expertise
- ▶ DoD specified testing capabilities (i.e. TDBI)
- ▶ Long-standing strategic partnerships & comprehensive supply-chain management
- ▶ Obsolescence mitigation
- ▶ Locked BOM under customer PCN control
- ▶ Localized Field Application Engineering for complete pre & post sale technical support



## MILITARY APPLICATIONS

Viking Technology's Multi-Chip Package products are designed for the rugged environment of military and space applications. They are rigorously tested and independently verified to MIL-STD-883 to operate in harsh environments:

- ▶ SWaP-optimized
- ▶ Space-constrained
- ▶ Vehicle-based
- ▶ High Shock & Vibration
- ▶ Ruggedized
- ▶ Harsh Environments
- ▶ Extended Temp

## REAL-WORLD APPLICATION DEPLOYMENTS

- ▶ Military Satellite
- ▶ Fighter Jets
- ▶ Unmanned Aerial Vehicles (UAV)
- ▶ Autonomous Vehicles
- ▶ Communication Satellites (LEO and Rad Tolerant)
- ▶ Communication Radio
- ▶ Embedded Satellite
- ▶ Avionics Video Capturing

For price and availability, please email us at [sales@vikingtechnology.com](mailto:sales@vikingtechnology.com).



### Global Locations

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